



Leti Innovation Days 2024  
Innovate, integrate, elevate

Semiconductors are today strategic high-tech components and indispensable in nearly all sectors of modern societies. Many functions are totally dependent on digitalization fuelled by integrated circuits & software and the demand for these technologies is strong and expanding.

The semiconductor industry is predicted an exponential growth to \$1T in 2030 due to trends such as AI, 5G/6G, IoT, quantum & neuromorphic computing, electric vehicles, etc. Automotive is the fastest growing market for semiconductors which are expected to represent 20% of the cost for a high-end electrical car in 2030.

To cope with this growing demand the semiconductor industry is now investing strongly and expects to have 103 new fabs operating between 2023-2030 worldwide including 11 fabs in Europe/Mideast.

Investment in EU is growing as well supported amongst others by EU Chips Act which has ambition to bolster EU semiconductor capabilities and ensure technological sovereignty. Several innovative projects are initiated under EU Chips Act, latest the FAMES Pilot Line a pioneering project aimed at advancing semiconductor technologies in Europe. It will enable disruptive system-on-chip architectures and provide smarter, greener and more efficient solutions for future chips paying attention to semiconductor sustainability.

The sustainability is a 360 degrees revolution where the ambitious targets in the Genesis project are 50% reduction in hazardous materials and 30% decrease in emissions and waste, and improved recycling of rare materials.

The Leti Innovation Days Conference 2024 (with the motto: innovate, integrate, elevate) gave a good impression of the R&D activities in the semiconductor industry and the focus on sustainability in the chip companies.



**Sébastien Dauvé, CEO Leti, we strongly believe the lab-to-fab model is the way forward**



**Michael Tchagaspanian, event chairman, Leti's startups creates advanced technologies**



**Jean-René Lèquepeys, CTO Leti, Europe needs faster transfer from lab to industrial products**



**Laith Altimime, president Semi Europe, automotive is the fastest growing semiconductor market**



**Fabio Gualandris, president Quality STM, we can now develop IPs very effectively**



**Fabio Gualandris receives a wafer-present from Sébastien Dauvé for recognition of the excellent cooperation**



Jean-Philippe Fricker, founder of Cerebras Systems, we make AI training easier



Sanjay Natarajan, SVP & GM, Intel Component Research, new materials needed to enable future compute power



David Anderson, president NY CREATES, R&D enable low cost IC solutions



Stefan Finkbeiner, CEO Bosch Sensortec, intelligent MEMS enable AI in the sensor itself



**Coby Hanoch, CEO Weebit Nano, ReRAM is perfect for edge AI**



**Coby Hanoch receives a wafer-present from Sébastien Dauvé for good and close cooperation**



**Theodore Sizer, EVP Nokia Bell Labs, Broadband communication is today an essential service**



**Bernhard Quendt, CTO Thales Group, we focus on green technology to understand climate phenomena**



Laura Matz, CSTO, Merck, we are striving to break siloed data ecosystems e.g. in the chip industry to leverage AI



Laura Matz receives a wafer-present from Sébastien Dauvé recognizing good relationship



Leroy Liu, CSO Realtek, we strive to introduce the cheapest chip to minimize AI training



Emmanuel Sabonnadière, EVP Soitec, our SmartSiC will be a standard in 2030 for power devices and modules



**Emmanuel Sabonnadière and Sébastien Dauvé (former and present CEO respectively at Leti) agree that smart SiC is a game changer in the semiconductor industry**